

## REMARKS

By this amendment, Applicants have amended claim 1 to include therein the limitation previously recited in dependent claim 2. Accordingly, claim 2 has been canceled. Applicants have amended the dependency of claims 3 and 4 so as to make these claims dependent on claim 1. Claim 1 has also been amended to end with a period.

Applicants note the Examiner has made the restriction requirement final. Applicants continue to traverse the restriction requirement for the reasons set forth in the response filed March 13, 2006. Applicants reserve the right to defer petition from the restriction requirement until after final action on or allowance of the claims to the invention elected. 37 CFR 1.144.

In view of the foregoing amendments to claim 1, reconsideration and withdrawal of the objection to claim 1 in numbered section 3 of the Office Action are requested.

Claims 1, 2 and 9 stand rejected under 35 U.S.C. 102(b) as allegedly being anticipated by U.S. patent application publication number US 2002/0161091 A1 to Amou et al. Applicants traverse this rejection and request reconsideration thereof.

Amou et al. is directed to a low dielectric loss tangent resin composition containing a crosslinking component having a weight average molecular weight of not more than 1,000 and a plurality of styrene groups and represented by the formula [1]; at least one member selected from a high polymer having a weight average molecular weight of not less than 5,000; and a filler.

Claim 4 of Amou et al. recites that the high polymer may be a homopolymer or copolymer of at least one monomer selected from butadiene, isoprene, styrene,

ethylstyrene, divinylbenzene, N-vinylphenylmaleimide, acrylic ester and acrylonitrile.

Paragraph 0054 of Amou et al. describes that rubber-like polymers comprising butadiene, isoprene, acrylic ester or the like impart flexibility, adhesive property and the smoothness of coating film to the cured product, and that styrene, ethylstyrene and acrylo-nitrile, when copolymerized with the above-mentioned rubber-like components, serve to improve the heat resistance of the product.

It is the Examiner's position that, based on these descriptions of Amou et al., one of ordinary skilled in the art would immediately envisage employing the rubber-like polymer containing styrene in the composition claimed in Claim 1 of Amou et al. However, Applicants disagree with this reasoning for the following reasons.

The resin composition as claimed in amended claim 1 comprises a rubber component having a weight averaged molecular weight of 5,000 or more and styrene units, in which the proportion of the carbon atoms and hydrogen atoms is 99% or more. Page 4, lines 15-18 of the present specification describes that the use of a rubber component in which the proportion of carbon atoms and hydrogen atoms is 99% or more in relation to all the chemical elements constituting the rubber component, preferably styrene-butadiene, permits further lowering of the dielectric dissipation factor. This effect is clearly demonstrated by the difference between the dielectric dissipation factor of Example 1, using Poly(acrylonitrile-co-butadiene-co-styrene) (ABS) as a rubber component, and the factor of Example 2, using Polystyrene-block-polybutadiene (BS) as a rubber component. The latter is almost one-tenth of the former. BS is composed only of carbon atoms and hydrogen atoms. This surprising difference indicates that the use of a rubber component in which the proportion of carbon atoms and hydrogen atoms is 99% or more can

effectively lower the dielectric dissipation factor.

Amou et al. merely describes that addition of a rubber-like component containing styrene is helpful for improving the heat resistance of the product. Additionally, no example described in Amou et al. employs a rubber-like component containing styrene. Amou et al. does not provide any hint as to what kind of rubber is helpful for lowering the dielectric dissipation factor. Amou et al. does not teach or suggest the effect that the use of a rubber component in which the proportion of the carbon atoms and hydrogen atoms is 99% or more serves to lower the dielectric dissipation factor.

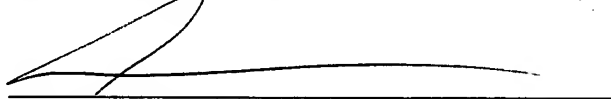
Therefore, Amou et al. does not anticipate the presently claimed invention.

In view of the foregoing amendments and remarks, favorable reconsideration and allowance of all the claims now in the application are requested.

It is respectfully requested that any shortage in the fee be charged to the deposit account of Antonelli, Terry, Stout & Kraus, LLP, Deposit Account No. 01-2135 (Case: 1021.43550X00).

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

A handwritten signature in black ink, appearing to read 'Alan E. Schiavelli', is written over a horizontal line.

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